

ABSTRACT

A system and method for processing a workpiece, such as a semiconductor wafer, includes a spray mechanism that rotates around the workpiece while the workpiece rests on a stationary workpiece support in a process chamber. The spray mechanism preferably includes one or more spray arms attached to a motorized rotary union via hollow elbow sections. The rotary union is attached to a fluid supply valve and preferably includes a hollow shaft through which process fluid may travel from the fluid supply valve to the spray arms. The process chamber includes a drain through which process fluid may be removed from the process chamber. A process gas and/or vapor manifold, a sonic transducer, and/or a rinsing liquid manifold may be included in the process chamber for delivering a process gas or vapor, sonic energy, and/or a rinsing liquid into the process chamber in order to enhance processing of the workpiece.